



DirectFET Medium Can RoHS Compliance Document

Contents:

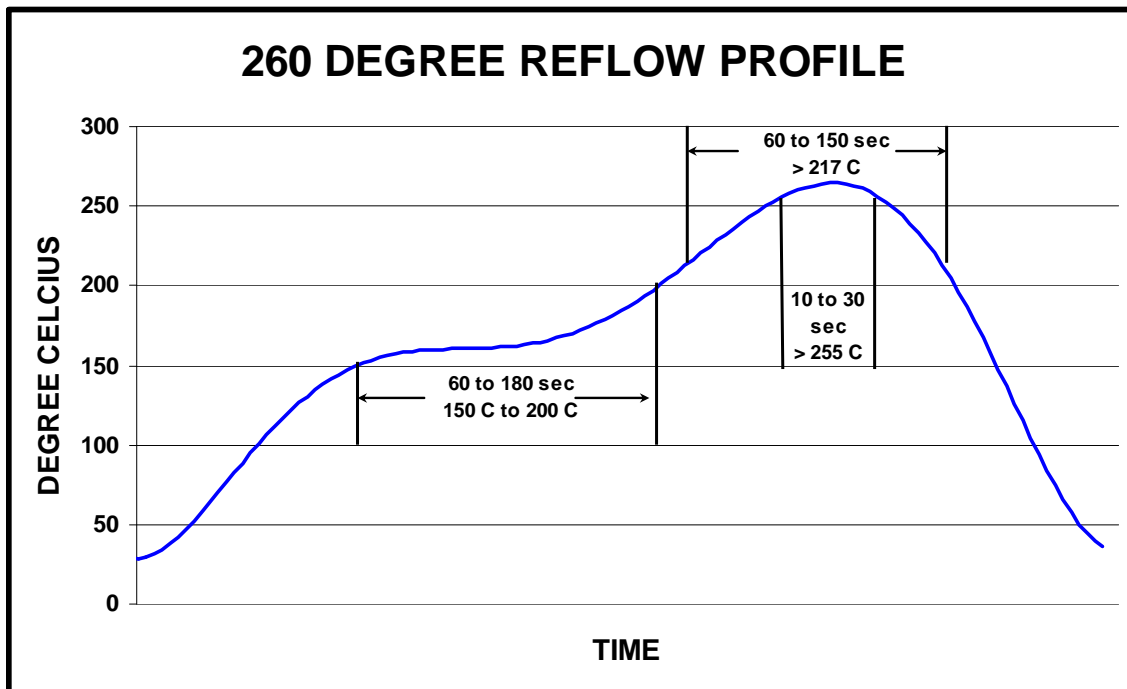
1. Composition
2. Solder Reflow



DirectFET – Medium Can

Component	Material Name	Material Mass (gr)	Substance Name	CAS Number	Substance Mass (g)	Substance Weight (%)	% of Total Weight
Chip	Silicon	0.00721	Si	7440-21-3	0.00687	95%	7.9%
			Epoxy	129915-35-1	0.00034	5%	0.4%
Lead Frame	Plated Copper	0.07662	Cu	7440-50-8	0.07500	98%	86.2%
			Ni	7440-02-0	0.00045	1%	0.5%
			Ag	7440-22-4	0.00117	2%	1.3%
Die Attach	Silver Epoxy	0.00187	Ag	7440-22-4	0.00140	75%	1.6%
			Epoxy	129915-35-1	0.00047	25%	0.5%
Solder	Solder Bumps	0.00135	Sn	7440-31-5	0.00126	93%	1.4%
			Ag	7440-22-4	0.00008	6%	0.1%
			Cu	7440-50-8	0.00001	1%	0.0%
MSL3 at 260 C		Total Weight (g)		0.08705			

No tin whisker mitigation strategy



This part is compliant with EU Directive 2002/95/EC (RoHS) and does not contain lead, mercury, cadmium (0.01%), hexavalent chromium, PBB or PBDE in concentrations greater than 0.1%, except as permitted by Annex (7).